

10-27-1998

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66793 U.S. PTO  
09/121180  
10/13/98

To: Honorable Commissioner of Patents and Trademarks:

Please record the attached original document(s) or copy thereof.

1. Name of conveying party(ies)  
a) Rao V. Annapragada  
b) Tekle M. Tafari  
c) Subhas Bothra
2. Name and address of receiving party(ies):  
a) Name: VLSI Technology, Inc.  
Address: 1109 McKay Drive  
San Jose, California 95131

10.13.98

3. Nature of conveyance
- |                                     |                    |                          |                   |
|-------------------------------------|--------------------|--------------------------|-------------------|
| <input checked="" type="checkbox"/> | Assignment         | <input type="checkbox"/> | Merger            |
| <input type="checkbox"/>            | Security Agreement | <input type="checkbox"/> | Change of Name    |
| <input type="checkbox"/>            | Other _____        | <input type="checkbox"/> | License Agreement |

Execution Date: October 7, 1998

4. Application Number(s) or Patent Number(s): 09/121,180

09/121180

The title of the (new) application is:

**PROCESS TO IMPROVE ADHESION OF PECVD CAP LAYERS IN INTEGRATED CIRCUITS**

5. Please send all correspondence concerning this (these) documents to:

**Jerry Wei**  
HICKMAN & MARTINE, LLP  
P.O. Box 52037  
Palo Alto, CA 94303-0746  
Tel. No.: (650) 470-7430  
Fax No.: (650) 470-7440

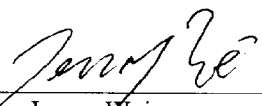
6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

- ☒ Enclosed  
☐ Authorized to be charged to Deposit Account No. 50-0384  
(Order No. \_\_\_\_\_)

8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date: October 13, 1998  
10/20/1998 RHIMS 00000024 09121180  
04 10:001 40.00

  
\_\_\_\_\_  
Jerry Wei  
Registration No. 43,247

Attorney Docket No. VTI1P201

(Revised 01/96)

**PATENT**  
**REEL: 9526 FRAME: 0708**

# ASSIGNMENT OF PATENT APPLICATION

Whereas we the undersigned inventors have invented certain new and useful improvements as set for in the patent application entitled:

## PROCESS TO IMPROVE ADHESION OF PECVD CAP LAYERS IN INTEGRATED CIRCUITS

(Atty. Docket No.: VTI1P201) for which we have executed an application for a United States Letters Patent that was filed in the U.S. Patent and Trademark Office on July 22, 1998, and which bears the application number 09/121,180.

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we the undersigned inventor hereby:

- 1) Sell(s), assign(s) and transfer(s) to **VLSI Technology**, a Delaware corporation having a place of business at 1109 McKay Drive, San Jose, CA 95131, (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor, as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the date indicated beside my signature.

1)	Signature: <u>Rao Annapragada</u>	Date: <u>10/7/98</u>
	Typed Name: Rao V. Annapragada	
1)	Signature: <u>Tekle Tafari</u>	Date: <u>10/7/98</u>
	Typed Name: Tekle M. Tafari	
1)	Signature: <u>Subhas Bothra</u>	Date: <u>10/7/98</u>
	Typed Name: Subhas Bothra	